# AUIRFS3206
AUIRFSL3206

**AUTOMOTIVE GRADE**

HEXFET® Power MOSFET

Features

- Advanced Process Technology
- Ultra Low On-Resistance
- Enhanced dV/dT and dI/dT capability
- 175°C Operating Temperature
- Fast Switching
- Repetitive Avalanche Allowed up to Tjmax
- Lead-Free, RoHS Compliant
- Automotive Qualified *
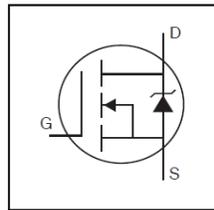
V_{DSS}		60V
$R_{DS(on)}$	typ.	2.4mΩ
	max.	3.0mΩ
I_{D} (Silicon Limited)		210A①
I_{D} (Package Limited)		120A

Description

Specifically designed for Automotive applications, this HEXFET® Power MOSFET utilizes the latest processing techniques to achieve extremely low on-resistance per silicon area. Additional features of this design are a 175°C junction operating temperature, fast switching speed and improved repetitive avalanche rating . These features combine to make this design an extremely efficient and reliable device for use in Automotive applications and a wide variety of other applications

D²Pak — AUIRFS3206
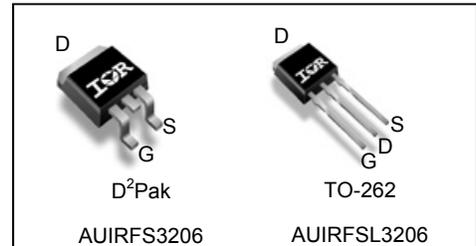
TO-262 — AUIRFSL3206

G	D	S
Gate	Drain	Source

Base part number	Package Type	Standard Pack		Orderable Part Number
		Form	**Quantity**	
AUIRFSL3206	TO-262	Tube	50	AUIRFSL3206
AUIRFS3206	D²-Pak	Tube	50	AUIRFS3206
		Tape and Reel Left	800	AUIRFS3206TRL

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (TA) is 25°C, unless otherwise specified.

Symbol	Parameter	Max.	Units
I_{D} @ T_{C} = 25°C	Continuous Drain Current, V_{GS} @ 10V (Silicon Limited)	210①	A
I_{D} @ T_{C} = 100°C	Continuous Drain Current, V_{GS} @ 10V (Silicon Limited)	150①	
I_{D} @ T_{C} = 25°C	Continuous Drain Current, V_{GS} @ 10V (Package Limited)	120	
I_{DM}	Pulsed Drain Current ②	840	
P_{D} @T_{C} = 25°C	Maximum Power Dissipation	300	W
	Linear Derating Factor	2.0	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy (Thermally Limited) ③	170	mJ
I_{AR}	Avalanche Current ②	See Fig.14,15, 22a, 22b	A
E_{AR}	Repetitive Avalanche Energy ②		mJ
dv/dt	Peak Diode Recovery ④	5.0	V/ns
T_{J} T_{STG}	Operating Junction and Storage Temperature Range	-55 to + 175	°C
	Soldering Temperature, for 10 seconds (1.6mm from case)	300	

Thermal Resistance

Symbol	Parameter	Typ.	Max.	Units
$R_{θJC}$	Junction-to-Case ⑨	——	0.50	°C/W
$R_{θJA}$	Junction-to-Ambient (PCB Mount), D² Pak⑧	——	40	

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*Qualification standards can be found at www.infineon.com

**Static @ T_J = 25°C (unless otherwise specified)**

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	60	——	——	V	V_{GS} = 0V, I_D = 250µA
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	——	0.07	——	V/°C	Reference to 25°C, I_D = 5mA ②
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	——	2.4	3.0	mΩ	V_{GS} = 10V, I_D = 75A ⑤
$V_{GS(th)}$	Gate Threshold Voltage	2.0	——	4.0	V	V_{DS} = V_{GS}, I_D = 150µA
gfs	Forward Trans conductance	210	——	——	S	V_{DS} = 50V, I_D = 75A
R_G	Gate Resistance	——	0.7	——	Ω	
I_{DSS}	Drain-to-Source Leakage Current	——	——	20	µA	V_{DS} = 60V, V_{GS} = 0V
		——	——	250		V_{DS} = 48V, V_{GS} = 0V, T_J =125°C
I_{GSS}	Gate-to-Source Forward Leakage	——	——	100	nA	V_{GS} = 20V
	Gate-to-Source Reverse Leakage	——	——	-100		V_{GS} = -20V

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

|	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge	——	120	170	nC	I_D = 75A
Q_{gs}	Gate-to-Source Charge	——	29	——		V_{DS} = 30V
Q_{gd}	Gate-to-Drain Charge	——	35	——		V_{GS} = 10V⑤
Q_{sync}	Total Gate Charge Sync. (Q_g - Q_{gd})	——	85	——		
$t_{d(on)}$	Turn-On Delay Time	——	19	——	ns	V_{DD} = 30V
t_r	Rise Time	——	82	——		I_D = 75A
$t_{d(off)}$	Turn-Off Delay Time	——	55	——		R_G= 2.7Ω
t_f	Fall Time	——	83	——		V_{GS} = 10V⑤
C_{iss}	Input Capacitance	——	6540	——	pF	V_{GS} = 0V
C_{oss}	Output Capacitance	——	720	——		V_{DS} = 50V
C_{rss}	Reverse Transfer Capacitance	——	360	——		f = 1.0MHz, See Fig. 5
$C_{oss\ eff.(ER)}$	Effective Output Capacitance (Energy Related)	——	1040	——		V_{GS} = 0V, V_{DS} = 0V to 48V⑦
$C_{oss\ eff.(TR)}$	Effective Output Capacitance (Time Related)	——	1230	——		V_{GS} = 0V, V_{DS} = 0V to 48V⑥

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	——	——	210①	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ②	——	——	840		
V_{SD}	Diode Forward Voltage	——	——	1.3	V	T_J = 25°C, I_S = 75A, V_{GS} = 0V ⑤
t_{rr}	Reverse Recovery Time	——	33	50	ns	T_J = 25°C $\quad V_{DD}$ = 51V
		——	37	56		T_J = 125°C $\quad I_F$ = 75A,
Q_{rr}	Reverse Recovery Charge	——	41	62	nC	T_J = 25°C $\quad$ di/dt = 100A/µs ⑤
		——	53	80		T_J = 125°C
I_{RRM}	Reverse Recovery Current	——	2.1	——	A	T_J = 25°C
t_{on}	Forward Turn-On Time					Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)
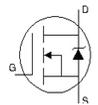
Notes:

① Calculated continuous current based on maximum allowable junction temperature. Bond wire current limit is 120A. Note that current limitations arising from heating of the device leads may occur with some lead mounting arrangements.

② Repetitive rating; pulse width limited by max. junction temperature.

③ Limited by $T_{Jmax,}$ starting T_J = 25°C, L = 0.023mH, R_G = 25Ω, I_{AS} = 120A, V_{GS} =10V. Part not recommended for use above this value.

④ $I_{SD} \leq$ 75A, di/dt $\leq$ 360A/µs, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq$ 175°C.

⑤ Pulse width $\leq$ 400µs; duty cycle $\leq$ 2%.

⑥ C_{oss} eff. (TR) is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS}.

⑦ C_{oss} eff. (ER) is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS}.

⑧ When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994

⑨ R_θ is measured at T_J approximately 90°C.
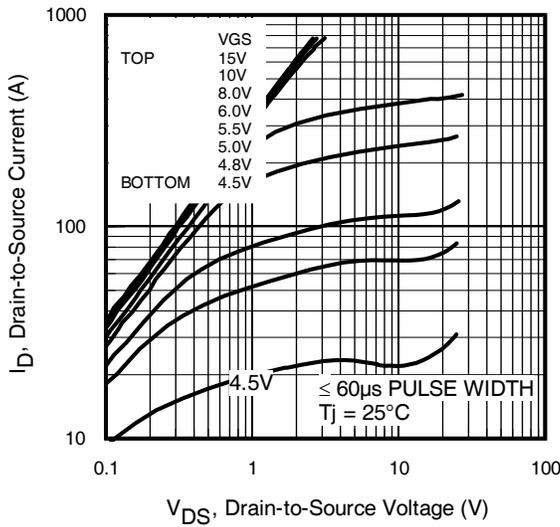
Fig. 1 Typical Output Characteristics
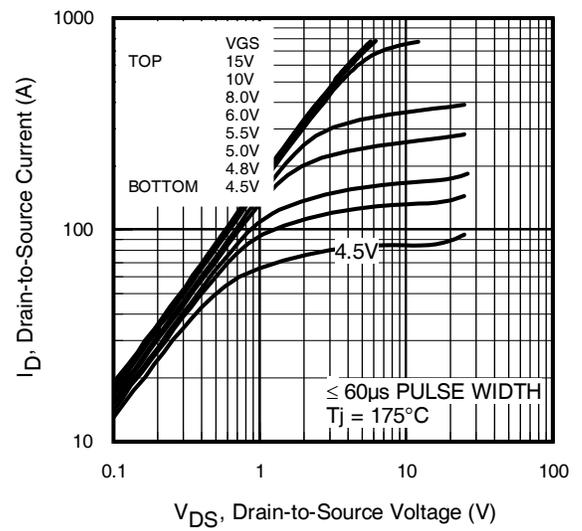
Fig. 2 Typical Output Characteristics
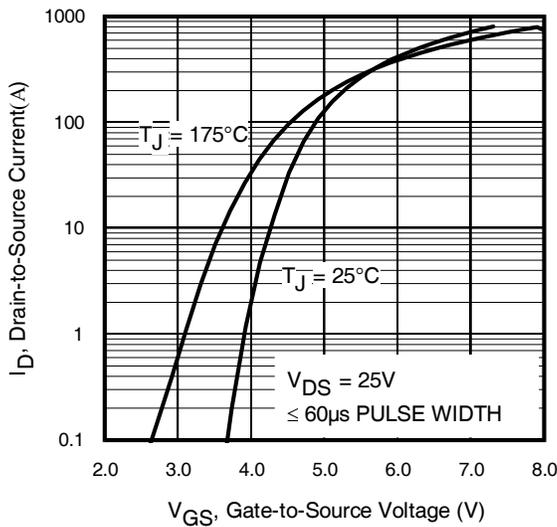
Fig. 3 Typical Transfer Characteristics
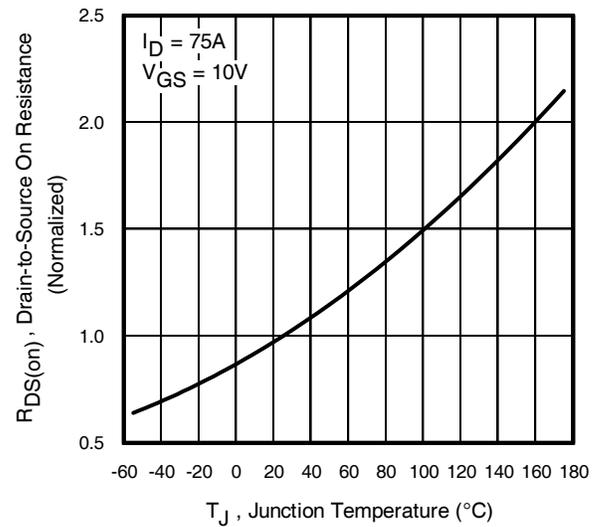
Fig. 4 Normalized On-Resistance vs. Temperature
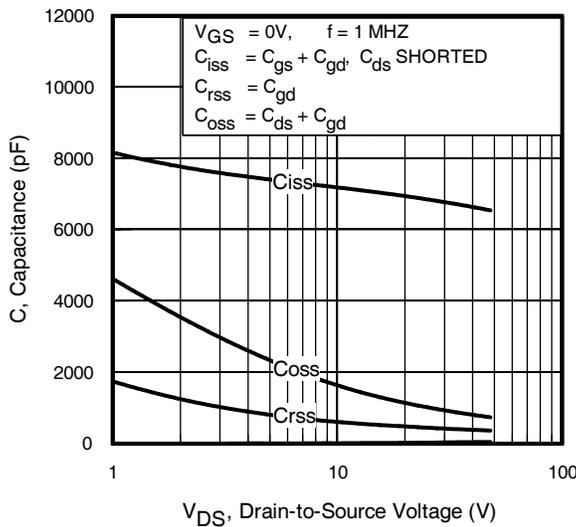
Fig 5. Typical Capacitance vs. Drain-to-Source Voltage
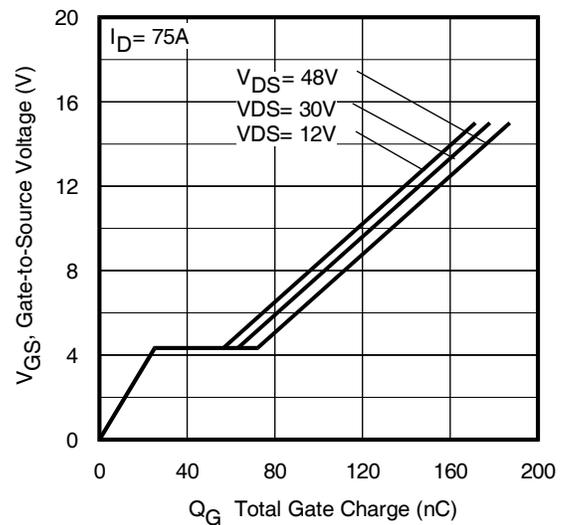
Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage

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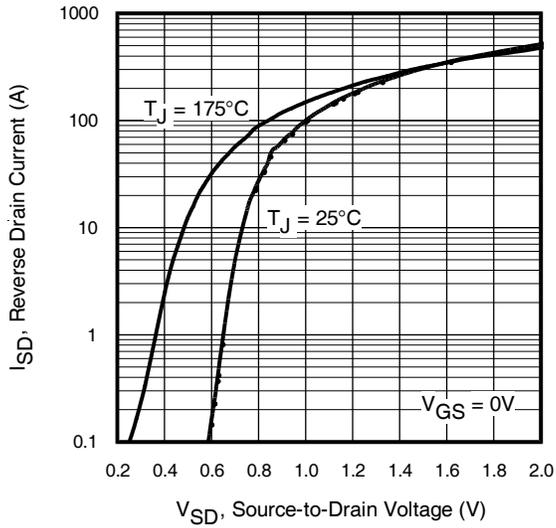
Fig. 7 Typical Source-to-Drain Diode
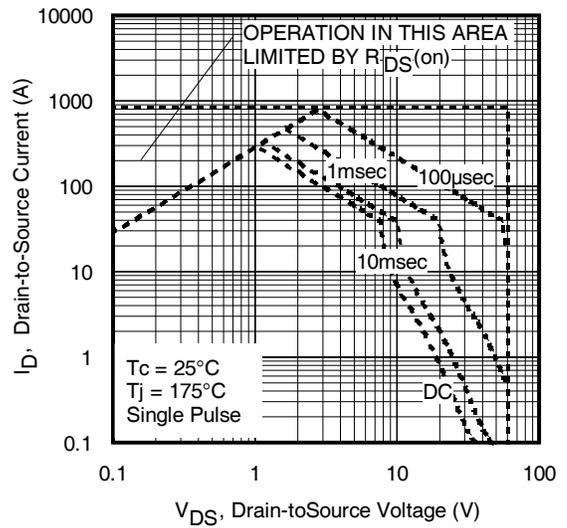
Fig 8. Maximum Safe Operating Area
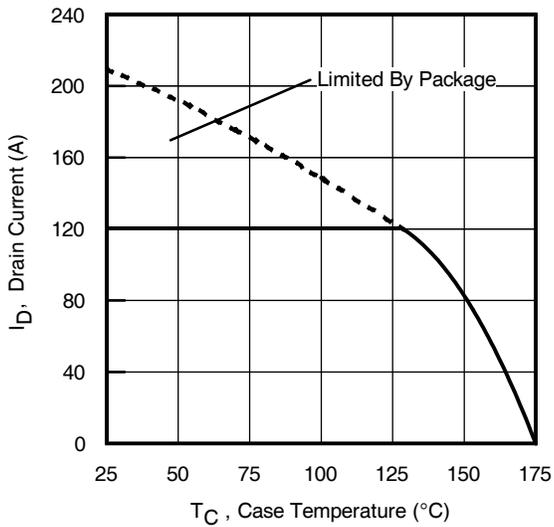
Fig 9. Maximum Drain Current vs. Case Temperature
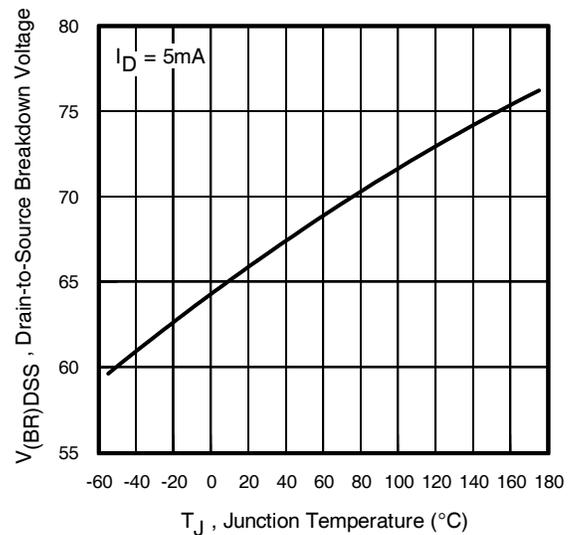
Fig 10. Drain-to-Source Breakdown Voltage
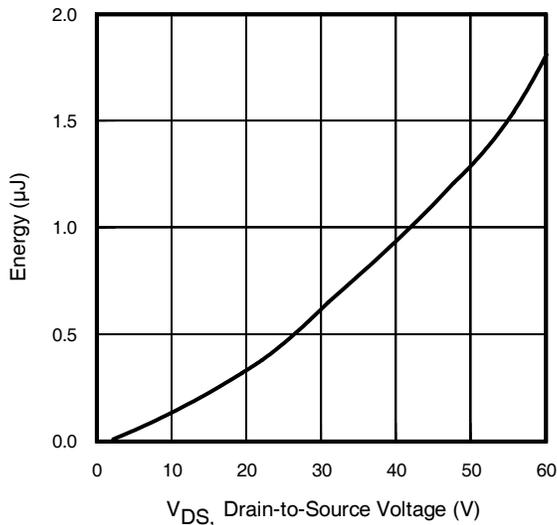
Fig 11. Typical C_{OSS} Stored Energy
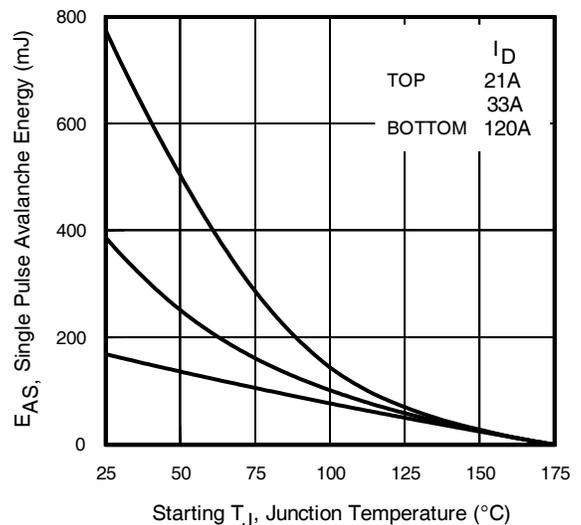
Fig 12. Maximum Avalanche Energy vs. Drain Current
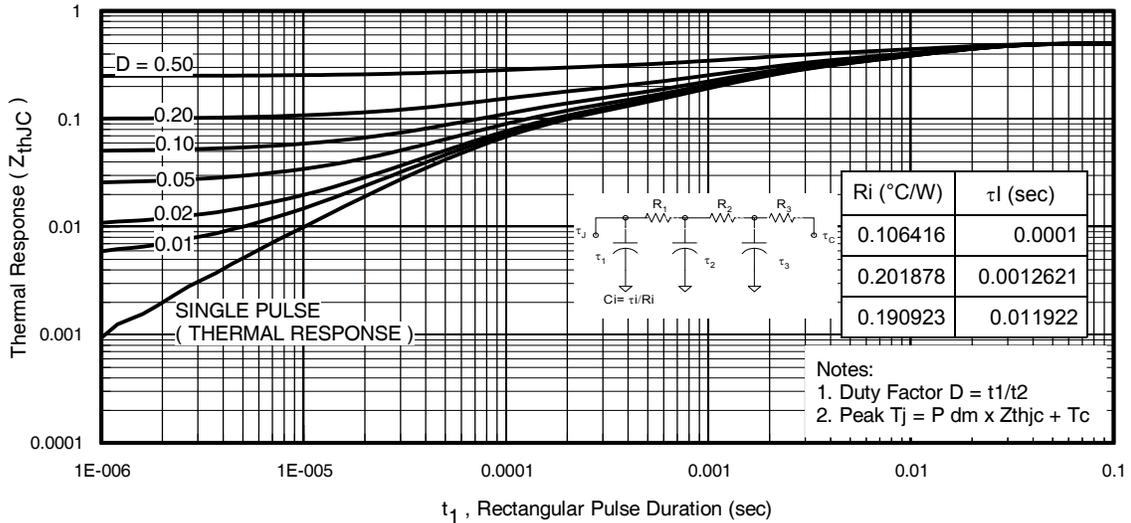
Fig 13. Maximum Effective Transient Thermal Impedance, Junction-to-Case

Ri (°C/W)	τI (sec)
0.106416	0.0001
0.201878	0.0012621
0.190923	0.011922

$C_i = \tau_i / R_i$

Notes:
1. Duty Factor D = t1/t2
2. Peak Tj = P dm x Zthjc + Tc
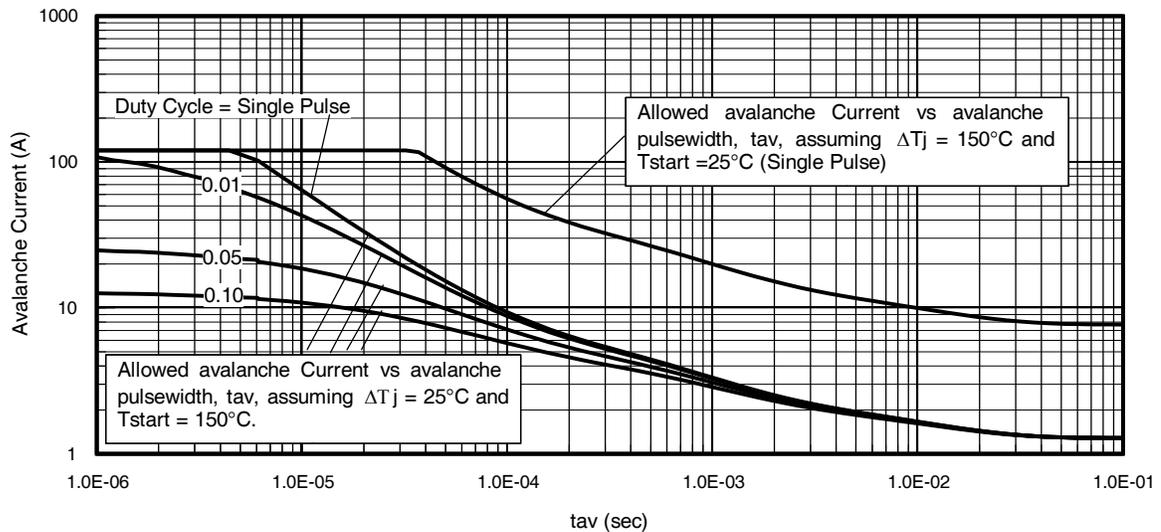
Fig 14. Avalanche Current vs. Pulse width

Fig 15. Maximum Avalanche Energy vs. Temperature
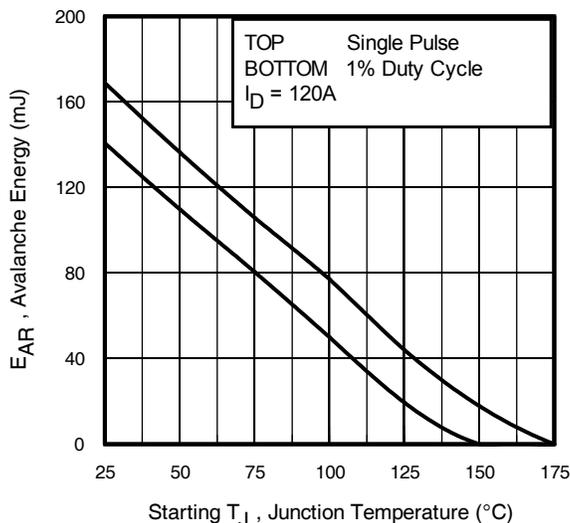
Notes on Repetitive Avalanche Curves , Figures 14, 15:
**(For further info, see AN-1005 at www.infineon.com)**

1. Avalanche failures assumption:
   Purely a thermal phenomenon and failure occurs at a temperature far in excess of T_{jmax}. This is validated for every part type.
2. Safe operation in Avalanche is allowed as long as T_{jmax} is not exceeded.
3. Equation below based on circuit and waveforms shown in Figures 18a, 18b.
4. $P_{D \, (ave)}$ = Average power dissipation per single avalanche pulse.
5. BV = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
6. I_{av} = Allowable avalanche current.
7. ΔT = Allowable rise in junction temperature, not to exceed T_{jmax} (assumed as 25°C in Figure 13, 14).
   t_{av} = Average time in avalanche.
   D = Duty cycle in avalanche = $t_{av} \cdot f$
 $Z_{thJC}(D, t_{av})$ = Transient thermal resistance, see Figures 13)

$$P_{D \, (ave)} = 1/2 \, (\, 1.3 \cdot BV \cdot I_{av}) = \Delta T / Z_{thJC}$$
$$I_{av} = 2\Delta T / [1.3 \cdot BV \cdot Z_{th}]$$
$$E_{AS \, (AR)} = P_{D \, (ave)} \cdot t_{av}$$

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Fig 16. Threshold Voltage vs. Temperature
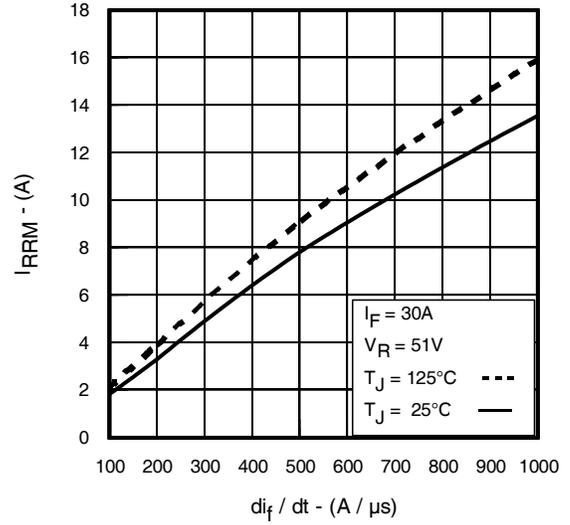
Fig. 17 - Typical Recovery Current vs. di$_f$/dt
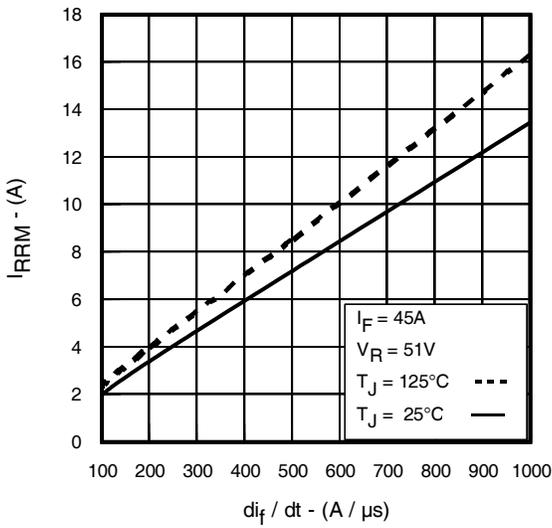
Fig. 18 - Typical Recovery Current vs. di$_f$/dt
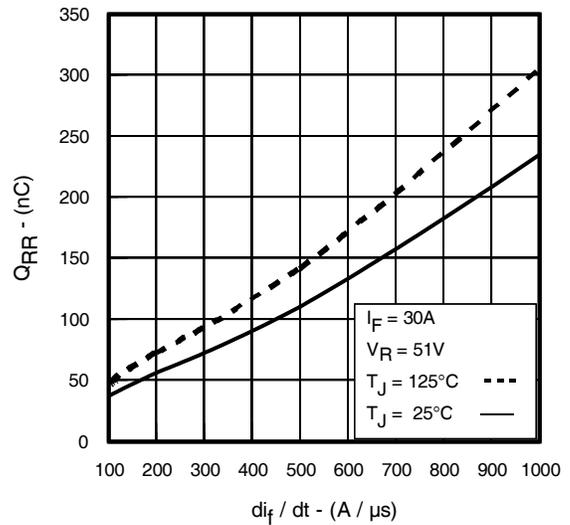
Fig. 19 - Typical Stored Charge vs. di$_f$/dt
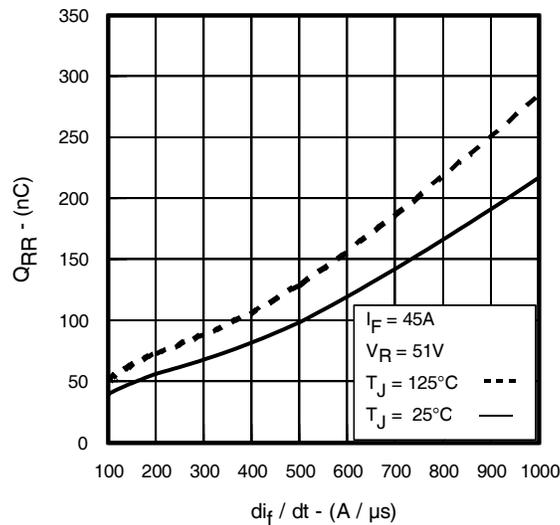
Fig. 20 - Typical Stored Charge vs. di$_f$/dt
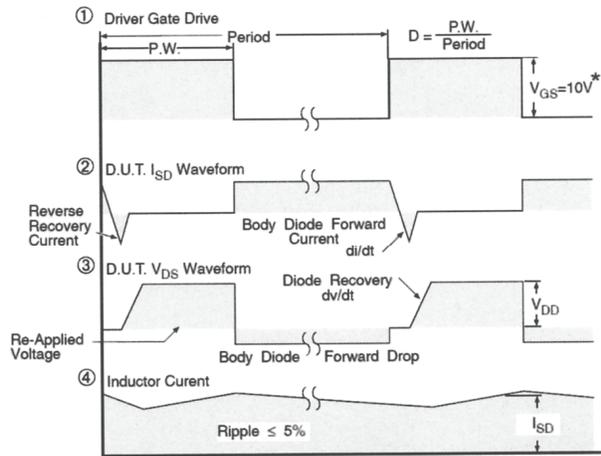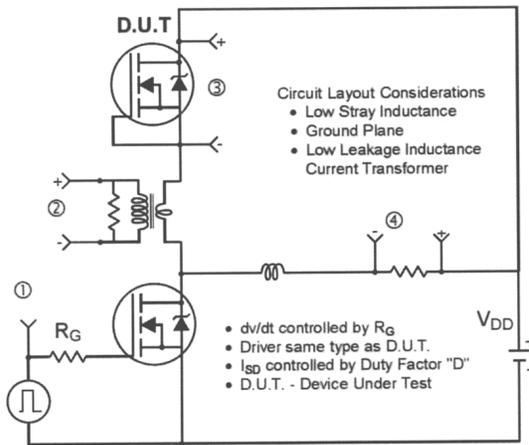
Fig 21. Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET® Power MOSFETs
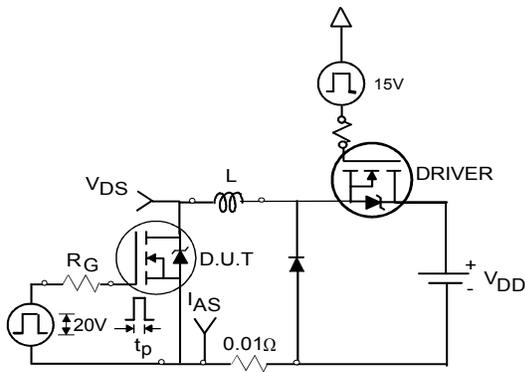
Fig 22a. Unclamped Inductive Test Circuit
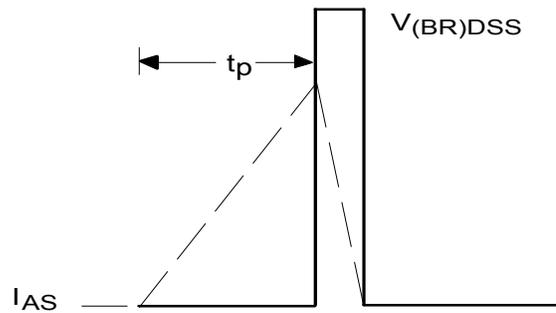
Fig 22b. Unclamped Inductive Waveforms
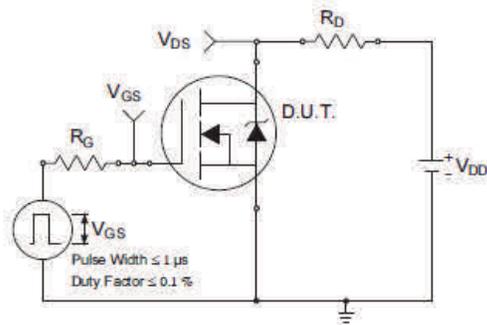
Fig 23a. Switching Time Test Circuit
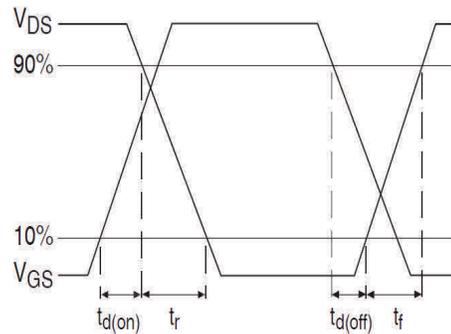

Fig 23b. Switching Time Waveforms
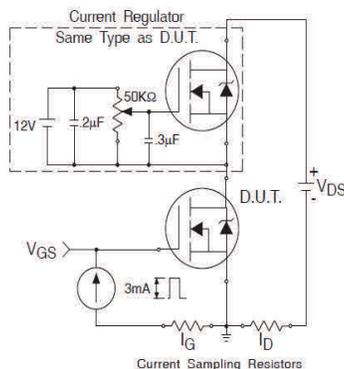
Fig 24a. Gate Charge Test Circuit
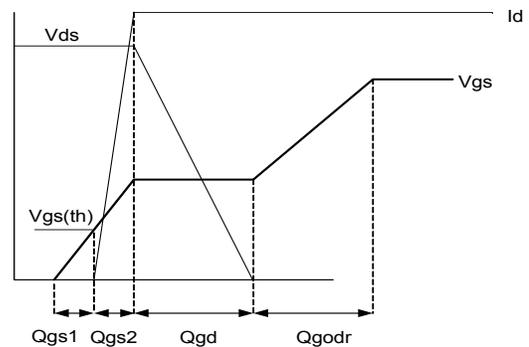
Fig 24b.   Gate Charge Waveform

2015-10-27

D²Pak (TO-263AB) Package Outline (Dimensions are shown in millimeters (inches))

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].

3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY AT DATUM H.

4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.

5. DIMENSION b1, b3 AND c1 APPLY TO BASE METAL ONLY.

6. DATUM A & B TO BE DETERMINED AT DATUM PLANE H.

7. CONTROLLING DIMENSION: INCH.

8. OUTLINE CONFORMS TO JEDEC OUTLINE TO-263AB.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	.160	.190	
A1	0.00	0.254	.000	.010	
b	0.51	0.99	.020	.039	
b1	0.51	0.89	.020	.035	5
b2	1.14	1.78	.045	.070	
b3	1.14	1.73	.045	.068	5
c	0.38	0.74	.015	.029	
c1	0.38	0.58	.015	.023	5
c2	1.14	1.65	.045	.065	
D	8.38	9.65	.330	.380	3
D1	6.86	—	.270	—	4
E	9.65	10.67	.380	.420	3,4
E1	6.22	—	.245	—	4
e	2.54 BSC		.100 BSC		
H	14.61	15.88	.575	.625	
L	1.78	2.79	.070	.110	
L1	—	1.68	—	.066	4
L2	—	1.78	—	.070	
L3	0.25 BSC		.010 BSC		

LEAD ASSIGNMENTS

DIODES
1.- ANODE (TWO DIE) / OPEN (ONE DIE)
2, 4.- CATHODE
3.- ANODE

HEXFET
1.- GATE
2, 4.- DRAIN
3.- SOURCE

IGBTs, CoPACK
1.- GATE
2, 4.- COLLECTOR
3.- EMITTER

D²Pak (TO-263AB) Part Marking Information

Part Number — AUFS3206

IR Logo — IOR   YWWA

XX • XX

Lot Code

Date Code
Y= Year
WW= Work Week

Note: For the most current drawing please refer to IR website at http://www.irf.com/package/

TO-262 Package Outline (Dimensions are shown in millimeters (inches)

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.
5. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
6. CONTROLLING DIMENSION: INCH.
7.– OUTLINE CONFORM TO JEDEC TO–262 EXCEPT A1(max.), b(min.) AND D1(min.) WHERE DIMENSIONS DERIVED THE ACTUAL PACKAGE OUTLINE.

LEAD ASSIGNMENTS

IGBTs, CoPACK

1.– GATE
2.– COLLECTOR
3.– EMITTER
4.– COLLECTOR

HEXFET   DIODES

1.– GATE   1.– ANODE (TWO DIE) / OPEN (ONE DIE)
2.– DRAIN   2, 4.– CATHODE
3.– SOURCE   3.– ANODE
4.– DRAIN

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	.160	.190	
A1	2.03	3.02	.080	.119	
b	0.51	0.99	.020	.039	
b1	0.51	0.89	.020	.035	5
b2	1.14	1.78	.045	.070	
b3	1.14	1.73	.045	.068	5
c	0.38	0.74	.015	.029	
c1	0.38	0.58	.015	.023	5
c2	1.14	1.65	.045	.065	
D	8.38	9.65	.330	.380	3
D1	6.86	–	.270	–	4
E	9.65	10.67	.380	.420	3,4
E1	6.22	–	.245		4
e	2.54 BSC		.100 BSC		
L	13.46	14.10	.530	.555	
L1	–	1.65	–	.065	4
L2	3.56	3.71	.140	.146	

TO-262 Part Marking Information

Part Number — AUFSL3206

IR Logo — IR

YWWA

Date Code
Y= Year
WW= Work Week

XX ● XX

Lot Code

Note: For the most current drawing please refer to IR website at http://www.irf.com/package/
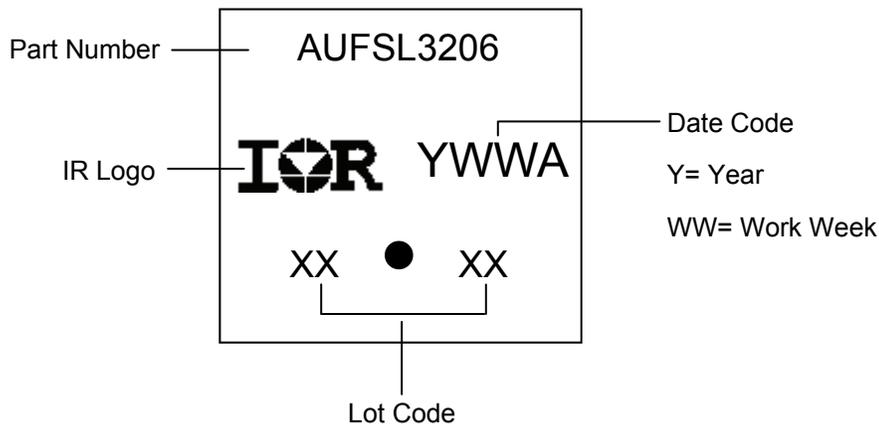
D²Pak (TO-263AB) Tape & Reel Information (Dimensions are shown in millimeters (inches))

TRR

FEED DIRECTION

TRL

FEED DIRECTION

1.60 (.063)
1.50 (.059)

⌀ 1.60 (.063)
1.50 (.059)

4.10 (.161)
3.90 (.153)

11.60 (.457)
11.40 (.449)

0.368 (.0145)
0.342 (.0135)

1.85 (.073)
1.65 (.065)

15.42 (.609)
15.22 (.601)

24.30 (.957)
23.90 (.941)

10.90 (.429)
10.70 (.421)

⌀ 1.75 (.069)
1.25 (.049)

4.72 (.136)
4.52 (.178)

16.10 (.634)
15.90 (.626)

13.50 (.532)
⌀ 12.80 (.504)

27.40 (1.079)
23.90 (.941)

④

⌀ 330.00
(14.173)
MAX.

⌀ 60.00 (2.362)
MIN.

30.40 (1.197)
MAX.

④

26.40 (1.039)
24.40 (.961)

③
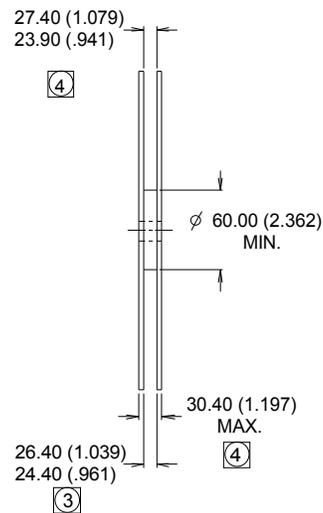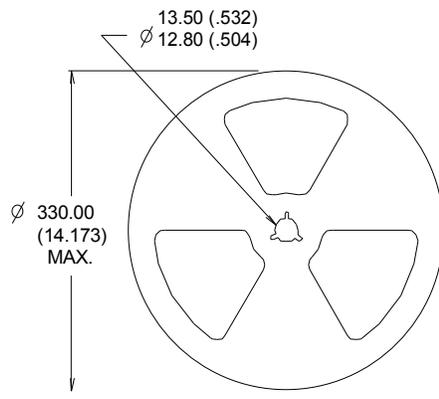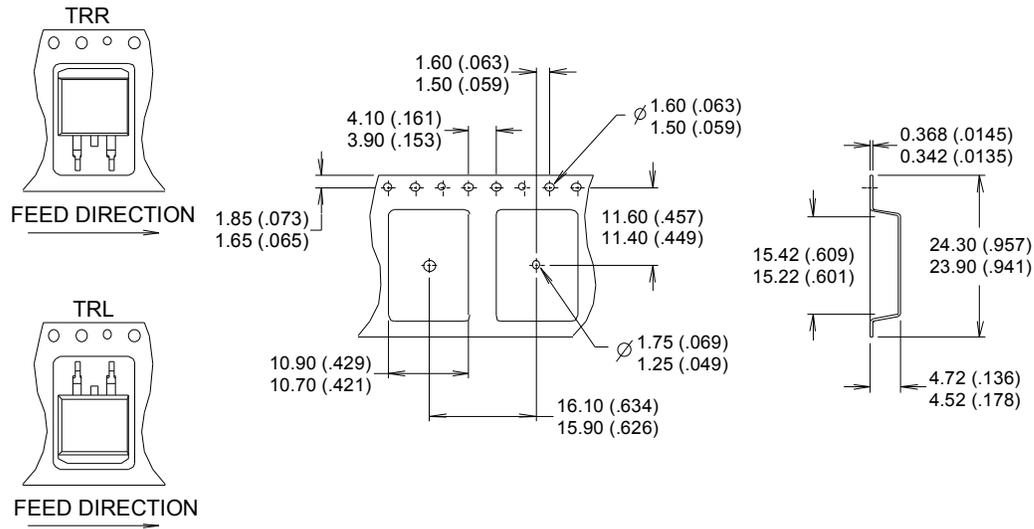
NOTES :
1. COMFORMS TO EIA-418.
2. CONTROLLING DIMENSION: MILLIMETER.
③ DIMENSION MEASURED @ HUB.
④ INCLUDES FLANGE DISTORTION @ OUTER EDGE.

Note: For the most current drawing please refer to IR website at http://www.irf.com/package/

Qualification Information

Qualification Level	Automotive (per AEC-Q101)	
	Comments: This part number(s) passed Automotive qualification. Infineon's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.	
Moisture Sensitivity Level	D^2-Pak	MSL1
	TO-262	
ESD	Machine Model	Class M4 (+/- 800V)† AEC-Q101-002
	Human Body Model	Class H2 (+/- 4000V)† AEC-Q101-001
	Charged Device Model	Class C5 (+/- 2000V)† AEC-Q101-005
RoHS Compliant	Yes	

† Highest passing voltage.

Revision History

Date	Comments
10/27/2015	• Updated datasheet with corporate template • Corrected ordering table on page 1.

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